

QUALITEK® 302
NO CLEAN
HALOGEN FREE FLUX

CORPORATE HEADQUARTERS USA: 315 Fairbank St. Addison, IL • 630-628-8083 • FAX 630-628-6543

EUROPE UK: Unit 9 Apex Ct. Bassendale Rd. Bromborough, Wirral CH62 3RE • 44 151 334 0888 • FAX 44 151 346 1408

ASIA-PACIFIC HEADQUARTERS SINGAPORE: 6 Tuas South St. 5 Singapore 637790 • 65 6795 7757 • FAX 65 6795 7767

PHILIPPINES: Phase 1 Qualitek Ave. Mariveles, Bataan Philippines C-2106 • 6347 935 4163 • FAX 63475613717

CHINA: 3B/F, YiPa Print Bldg. 351 # JiHua Rd., Buji Shenzhen, China 518112 • 86 755 28522814 • FAX 86 755 28522787

Description

302 No Clean flux is a homogeneous mixture of halogen-free, low solids, organic flux designed for wave soldering conventional or surface mount PCB assemblies. 302 provides superior foaming characteristics with a uniform, stable head of small bubbles. 302 exhibits excellent wetting and fluxing activities with essentially no residue left on the assembly after soldering. 302 may be used for both leaded and lead-free applications.

Main Features

- Halogen-free
- Excellent wetting
- Bright, shiny solder joints
- Low residue
- Rosin/Resin free
- Compatible with Lead-Free & Leaded Solder Systems

Physical Properties

	Specification	Test Method
Flux Classification	ORL0	IPC-J-STD-004B
Color and Appearance	Light straw liquid	
Specific Gravity (g/cm³)	0.800 ± 0.006	IPC-J-STD-004B
SIR	1.20 x 10 ¹¹ ohms	IPC-TM-650 2.6.3.3
Solids	2.3 ± 0.3	
Acid Number (mgKOH/g)	18.0 – 21.0	Titration

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Applications

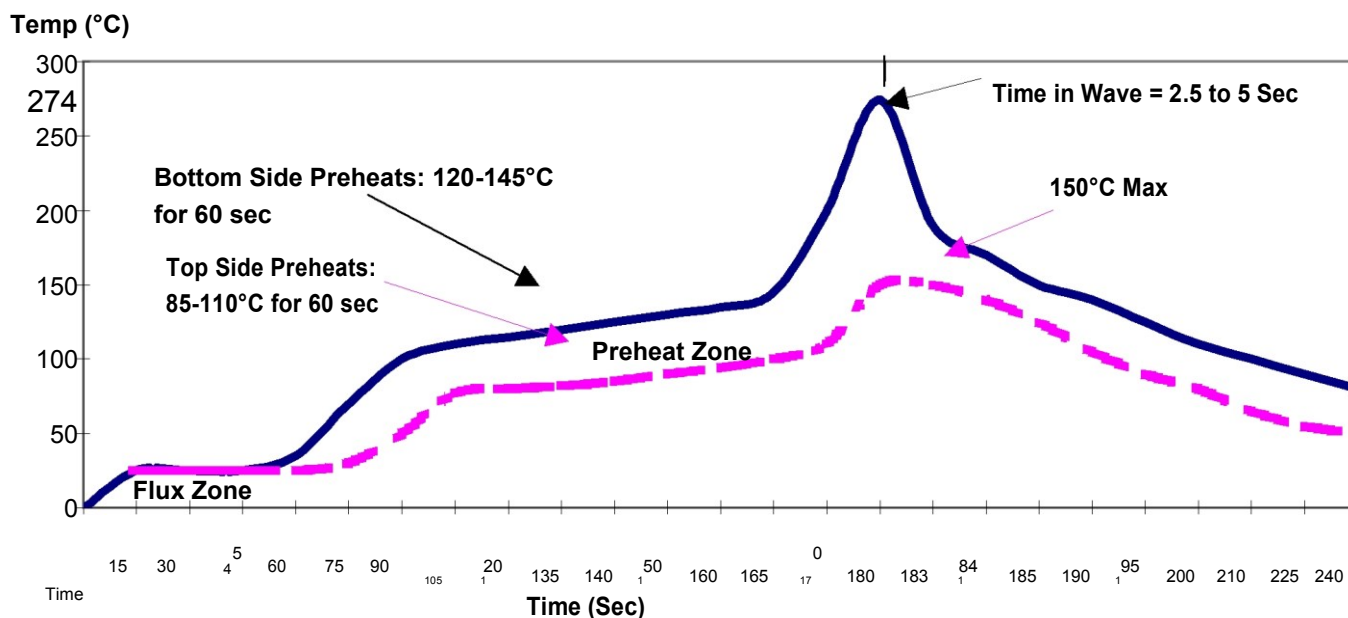
Flux Application

For mass wave soldering of OSP and plated circuit boards, spray, foam or wave fluxing can be utilized to apply this flux. Flux deposition density and uniformity are critical to successful use of low solids no-clean flux. If foam fluxing, the foam fluxer should be supplied with compressed air, which is free of oil and water. The flux tank should be full at all times. The surface of the flux should be 1-½ inches above the top of the flux aerator, or flux stone. Pressure should then be adjusted to produce the optimum foam height with a fine uniform foam head. After fluxing, an air knife should be used to remove excessive flux from the assembly.

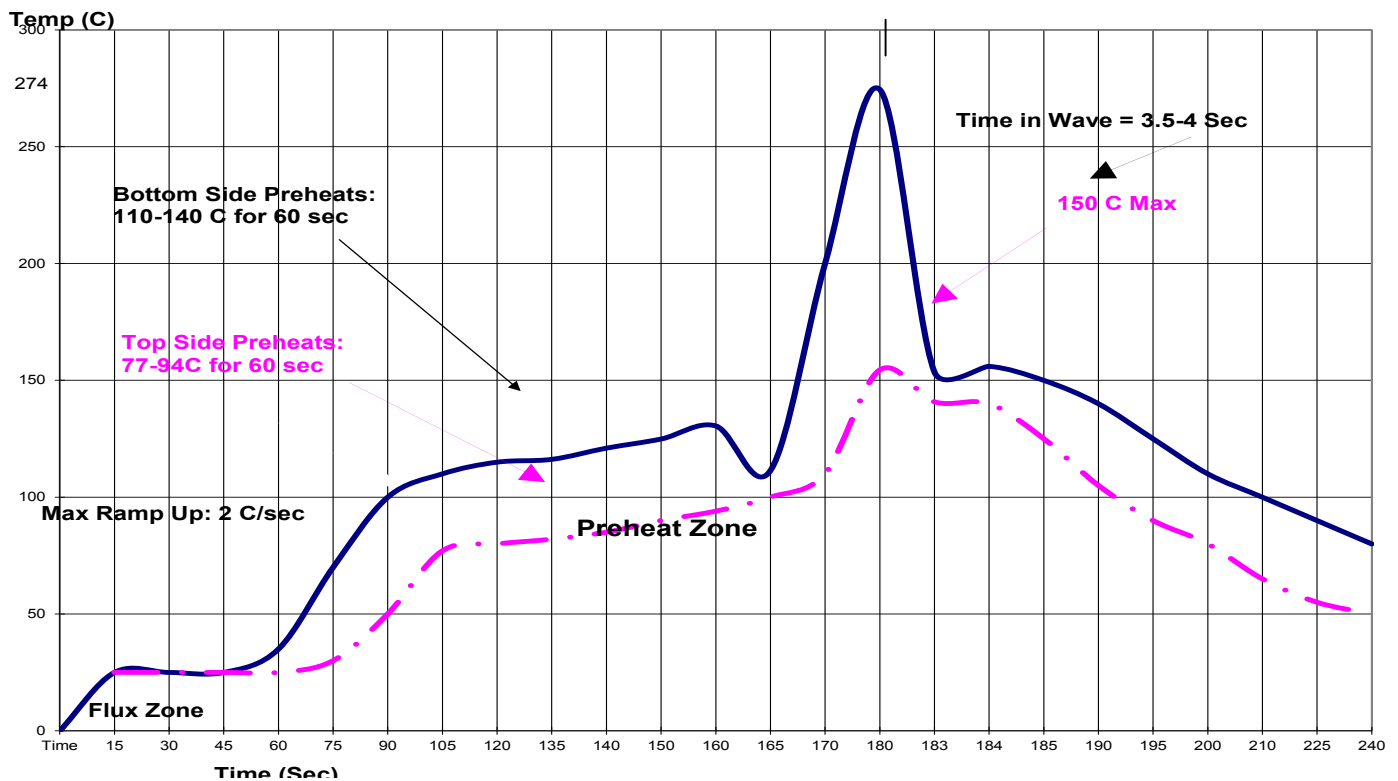
Uniformity of the spray flux coating can be visually checked by running a tempered glass plate (usually supplied by machine manufacturer) through the spray and preheat sections, and inspected before going across the wave.

OPERATING PARAMETERS		TYPICAL LEVEL
Amount of flux		Foam, Wave: 1000-2000 µg/in ² solids Spray: 750-1500 µg/in ² solids Drop Jet- 600-1200 µg/in ² solids
Foam Fluxing Parameters		
	Foam Stone Pore Size	20-50 µm
	Flux Level Above Stone	1-1 ½ inches (25-40mm)
	Chimney Opening	3/8-1/2 inch (10-13 mm)
	Air Pressure	1-2 psi
Top Side Preheat Temperature		190-230 °F (85-110 °C)
Bottom Side Preheat Temperature		65 °F (35 °C) higher than topside
Conveyor Speed		4-6 feet/minute(1.2-1.8 meters/minute)
Contact Time in the Solder (including Chip & Lambda)		2.5-4.5 seconds
Solder Pot Temperature		
	Sn96.5/Ag3.5	500-530 °F (260-276 °C)
	Sn95/Ag5	536-565 °F (280-296 °C)
	Sn99.3/0.7Cu	510-530 °F (265-276 °C)
	SnAgCu	520-530 °F (271-276 °C)
	Sn95/Sb5	536-565 °F (280-296 °C)

TYPICAL Lead Free Wave Solder Profile (SNAGCU)



TYPICAL Leaded Wave Solder Profile (Sn63/Pb37)



Process Control

Control of flux during use is necessary to assure consistent flux deposition on the circuit board. Due to the very low solids content of no clean fluxes, specific gravity is not an accurate measure for assessing solids content. Monitoring and controlling acid number by titration is recommended for maintaining the proper flux concentration. Control of the flux can be achieved with 300A thinner to maintain fluxing activity.

Over time debris and contaminants may accumulate in the flux reservoir. Therefore, periodically replacing the flux and cleaning the reservoir is recommended for consistent performance and minimizing debris build-up.

Cleaning

302 is a no clean formulation therefore the residues do not need to be removed for typical applications. If residue removal is desired, the use of Everklean 1005 Buffered Saponifier with a 5-15% concentration in hot 60 °C (140 °F) will aid in residue removal.

Storage & Shelf Life

Liquid flux should be stored in a 65-80°F environment away from direct heat and flame. Shelf life is 2 years from date of manufacture.

Packaging

302 No Clean Halogen Free Flux is available in

- 1 Gallon/1 Liter containers
- 5 Gallon/5 Liter containers
- 55 Gallon/20 Liter containers

Disposal

302 contains hazardous ingredients therefore the flux should be disposed of in accordance with federal, state, and local authority requirements.

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